

EVLYS LTD. - POWER SEMICONDUCTORS DEVICES -
Wholesale and Retail.

Phase Control Disc Thyristor Type DT56-1000-28

High power cycling capability / Low on-state and switching losses
 Designed for traction and industrial applications

Mean on-state current	I _{TAV}	1000 A			
Repetitive peak off-state voltage	V _{DRM}	2000 ÷ 2800 V			
Repetitive peak reverse voltage	V _{RRM}				
Turn-off time	t _q	320, 400, 500 µs			
V _{DRM} , V _{RRM} , V	2000	2200	2400	2600	2800
Voltage code	20	22	24	26	28
T _j , °C			-60 ÷ 125		

MAXIMUM ALLOWABLE RATINGS

Symbols and parameters		Units	Values	Test conditions	
ON-STATE					
I _{TAV}	Mean on-state current	A	1000 1225	T _c =95 °C, Double side cooled T _c =85 °C, Double side cooled 180° half-sine wave; 50 Hz	
I _{TRMS}	RMS on-state current	A	1570	T _c =95 °C, Double side cooled 180° half-sine wave; 50 Hz	
I _{TSM}	Surge on-state current	kA	23.0 26.0	T _j =T _{j max} T _j =25 °C	180° half-sine wave; t _p =10 ms; single pulse; V _D =V _R =0 V; Gate pulse: I _G =2 A; t _{GP} =50 µs; di _G /dt≥1 A/µs
			24.0 28.0	T _j =T _{j max} T _j =25 °C	180° half-sine wave; t _p =8.3 ms; single pulse; V _D =V _R =0 V; Gate pulse: I _G =2 A; t _{GP} =50 µs; di _G /dt≥1 A/µs
I ² t	Safety factor	A ² ·10 ³	2600 3300	T _j =T _{j max} T _j =25 °C	180° half-sine wave; t _p =10 ms; single pulse; V _D =V _R =0 V; Gate pulse: I _G =2 A; t _{GP} =50 µs; di _G /dt≥1 A/µs
			2300 3200	T _j =T _{j max} T _j =25 °C	180° half-sine wave; t _p =8.3 ms; single pulse; V _D =V _R =0 V; Gate pulse: I _G =2 A; t _{GP} =50 µs; di _G /dt≥1 A/µs
BLOCKING					
V _{DRM} , V _{RRM}	Repetitive peak off-state and Repetitive peak reverse voltages	V	2000÷2800	T _{j min} < T _j <T _{j max} ; 180° half-sine wave; 50 Hz; Gate open	
V _{DSM} , V _{RSM}	Non-repetitive peak off-state and Non-repetitive peak reverse voltages	V	2100÷2900	T _{j min} < T _j <T _{j max} ; 180° half-sine wave; single pulse; Gate open	
V _D , V _R	Direct off-state and Direct reverse voltages	V	0.6·V _{DRM} 0.6·V _{RRM}	T _j =T _{j max} ; Gate open	

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TRIGGERING				
I_{FGM}	Peak forward gate current	A	8	
V_{RGM}	Peak reverse gate voltage	V	5	$T_j = T_{j \max}$
P_G	Gate power dissipation	W	4	$T_j = T_{j \max}$ for DC gate current
SWITCHING				
$(di_T/dt)_{crit}$	Critical rate of rise of on-state current non-repetitive ($f=1$ Hz)	A/ μ s	2000	$T_j = T_{j \max}; V_D = 0.67V_{DRM}; I_{TM} = 4000 A; Gate pulse: I_G = 2 A; t_{GP} = 50 \mu s; di_G/dt \geq 2 A/\mu s$
THERMAL				
T_{stg}	Storage temperature	°C	-60÷50	
T_j	Operating junction temperature	°C	-60÷125	
MECHANICAL				
F	Mounting force	kN	24.0÷28.0	
a	Acceleration	m/s ²	50	Device clamped

CHARACTERISTICS

Symbols and parameters		Units	Values	Conditions
ON-STATE				
V_{TM}	Peak on-state voltage, max	V	1.75	$T_j = 25^\circ C; I_{TM} = 3140 A$
$V_{T(TO)}$	On-state threshold voltage, max	V	0.928	$T_j = T_{j \max};$
r_T	On-state slope resistance, max	$m\Omega$	0.295	$0.5 \pi I_{TAV} < I_T < 1.5 \pi I_{TAV}$
I_L	Latching current, max	mA	1500	$T_j = 25^\circ C; V_D = 12 V;$ Gate pulse: $I_G = 2 A;$ $t_{GP} = 50 \mu s; di_G/dt \geq 1 A/\mu s$
I_H	Holding current, max	mA	300	$T_j = 25^\circ C;$ $V_D = 12 V;$ Gate open
BLOCKING				
I_{DRM}, I_{RRM}	Repetitive peak off-state and Repetitive peak reverse currents, max	mA	150	$T_j = T_{j \max};$ $V_D = V_{DRM}; V_R = V_{RRM}$
$(dv_D/dt)_{crit}$	Critical rate of rise of off-state voltage ¹⁾ , min	V/ μ s	200, 320, 500, 1000, 1600, 2000, 2500	$T_j = T_{j \max};$ $V_D = 0.67V_{DRM};$ Gate open
TRIGGERING				
V_{GT}	Gate trigger direct voltage, max	V	3.00 2.50 1.50	$T_j = T_{j \min}$ $T_j = 25^\circ C$ $T_j = T_{j \max}$
I_{GT}	Gate trigger direct current, max	mA	400 250 150	$T_j = T_{j \min}$ $T_j = 25^\circ C$ $T_j = T_{j \max}$
V_{GD}	Gate non-trigger direct voltage, min	V	0.35	$T_j = T_{j \max};$
I_{GD}	Gate non-trigger direct current, min	mA	45.00	$V_D = 0.67V_{DRM};$ Direct gate current
SWITCHING				
t_{gd}	Delay time, max	μ s	1.25	$T_j = 25^\circ C; V_D = 1500 V; I_{TM} = I_{TAV};$ $di/dt = 200 A/\mu s;$
t_{gt}	Turn-on time	μ s	8.00	Gate pulse: $I_G = 2 A; V_G = 20 V;$ $t_{GP} = 50 \mu s; di_G/dt = 2 A/\mu s$
t_q	Turn-off time ²⁾ , max	μ s	320, 400, 500	$dv_D/dt = 50 V/\mu s; T_j = T_{j \max}; I_{TM} = I_{TAV};$ $di_R/dt = -10 A/\mu s; V_R = 100 V;$ $V_D = 0.67V_{DRM}$
Q_{rr}	Total recovered charge, max	μC	3640	$T_j = T_{j \max}; I_{TM} = 1000 A;$
t_{rr}	Reverse recovery time, max	μ s	40	$di_R/dt = -10 A/\mu s;$
I_{rrM}	Peak reverse recovery current, max	A	182	$V_R = 100 V$

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THERMAL					
R_{thjc}	Thermal resistance, junction to case, max	$^{\circ}\text{C}/\text{W}$	0.0180	Direct current	Double side cooled
R_{thjc-A}			0.0396		Anode side cooled
R_{thjc-K}			0.0324		Cathode side cooled
R_{thck}	Thermal resistance, case to heatsink, max	$^{\circ}\text{C}/\text{W}$	0.0040	Direct current	

MECHANICAL					
w	Weight, max	g	510		
D_s	Surface creepage distance	mm (inch)	30.38 (1.196)		
D_a	Air strike distance	mm (inch)	18.05 (0.710)		

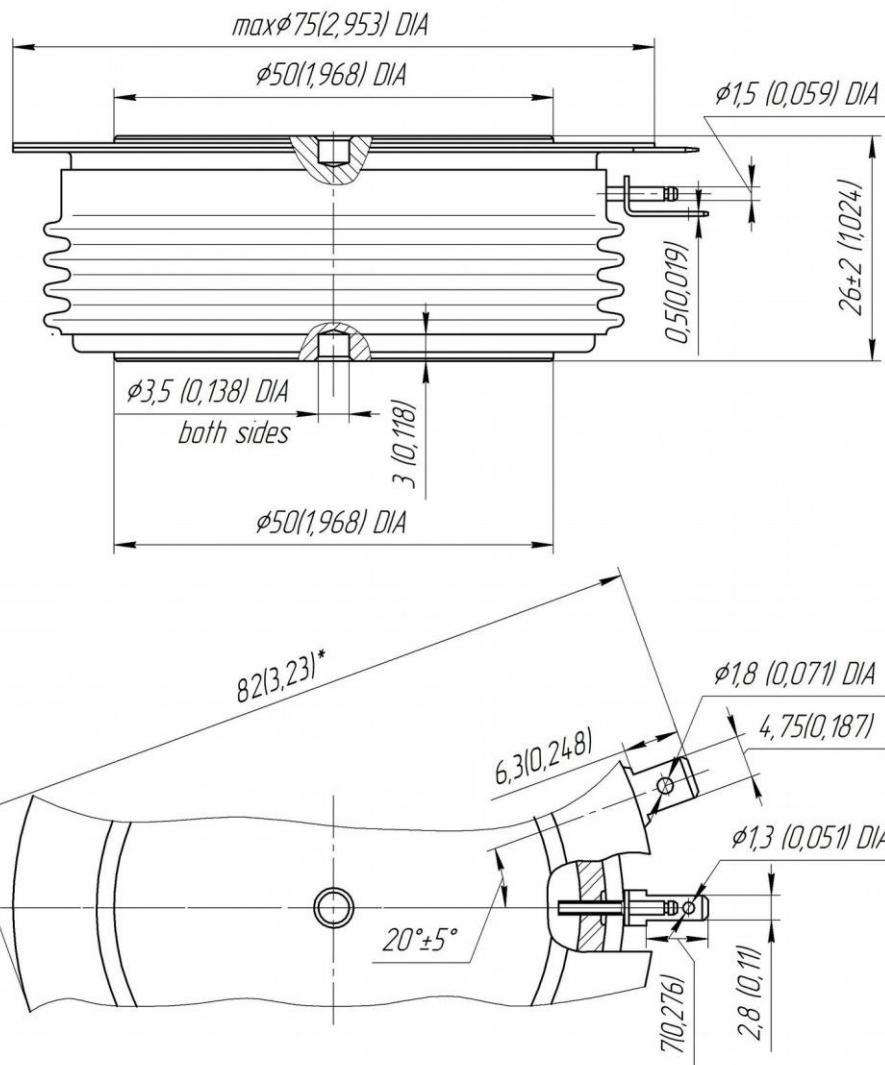
PART NUMBERING GUIDE						NOTES								
DT	56	1000	28	7	3	1) Critical rate of rise of off-state voltage								
1	2	3	4	5	6	Symbol of Group $(dv_D/dt)_{crit}, \text{V}/\mu\text{s}$	4	5	6	7	8	8.5	9	
1. DT - Phase Control Disc Thyristor						200 320 500 1000 1600 2000 2500								
2. Element Diameter						2) Turn-off time ($dv_D/dt=50 \text{ V}/\mu\text{s}$)								
3. Mean on-state current, A						Symbol of Group $t_{off}, \mu\text{s}$	0	0	0	0	0	0	0	
4. Voltage code						320 400 500								
5. Critical rate of rise of on-state current non-repetitive, $\text{V}/\mu\text{s}$														
6. Turn-off time ($dv_D/dt=50 \text{ V}/\mu\text{s}$)														

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OVERALL DIMENSIONS

Package type: T.D5



All dimensions in millimeters (inches)